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## (54)**Hermetically Glass Sealed Pressure Sensor**

(57)Techniques disclosed herein include systems and methods for pressure measurement of fluids including vehicular fluids. The pressure sensor includes a microelectromechanical system (MEMS) sensor (130) for pressure measurement. The MEMS sensor (130) is attached to a glass tube (120)which is compressively sealed to a mounting frame (105) that is attachable to a pressure port of a fluid-containing enclosure. Techniques disclosed herein provide an hermetic seal between the tube (120) and the mounting frame and a rigid seal (140) between the MEMS sensor to a pressure sensor while decoupling thermal expansion stress from the MEMS sensor. With such decoupling techniques, pressure sensing reliability and accuracy can be improved because thermal expansion stress is decoupled from the MEMS sensor. Such techniques provide an accurate, durable, and cost-effective pressure sensor.

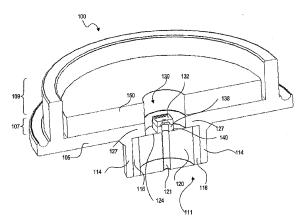


FIG. 1